



Material Content Data Sheet



Sales Product Name	TLE6208-6G			Issued	7. August 2019			
MA#	MA005353736							
Package	PG-DSO-28-41			Weight*	835.35 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.614	1.75	1.75	17495	17495
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		87	
	non noble metal	zinc	7440-66-6	0.292	0.03		349	
	non noble metal	iron	7439-89-6	5.837	0.70		6988	
wire	non noble metal	copper	7440-50-8	237.007	28.37	29.11	283724	291148
	non noble metal	copper	7440-50-8	1.274	0.15	0.15	1526	1526
	encapsulation	organic material	carbon black	1333-86-4	1.131	0.14		1354
encapsulation	plastics	epoxy resin	-	52.025	6.23		62280	
	inorganic material	silicondioxide	60676-86-0	512.337	61.33	67.70	613323	676957
leadfinish	non noble metal	tin	7440-31-5	4.913	0.59	0.59	5882	5882
plating	noble metal	silver	7440-22-4	1.897	0.23	0.23	2271	2271
glue	plastics	epoxy resin	-	0.986	0.12		1180	
	noble metal	silver	7440-22-4	2.958	0.35	0.47	3541	4721
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com